

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L60	1	"324"/\$ and strip with (die dice) with ((locat\$4 position) and ((database data adj base) (camera vision)))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/03 15:36
L59	35	"324"/\$ and strip with (die dice) with ((locat\$4 position) (database data adj base) (camera vision))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/03 15:36
L48	10	"700"/\$ and strip with (die dice) with ((locat\$4 position) (database data adj base) (camera vision))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/03 15:33
L57	5	strip with (die dice) same ((locat\$4 position) and ((database data adj base) and (camera vision)))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/03 14:37
L56	9	strip with (die dice) with ((locat\$4 position) and ((database data adj base) (camera vision)))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/03 14:37
L47	2157	strip with (die dice) with ((locat\$4 position) (database data adj base) (camera vision))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/03 14:06
L55	141	"257"/\$ and strip with (die dice) with ((locat\$4 position) (database data adj base) (camera vision))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/03 14:02
L54	24	"235"/\$ and strip with (die dice) with ((locat\$4 position) (database data adj base) (camera vision))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/03 14:02
L53	278	"156"/\$ and strip with (die dice) with ((locat\$4 position) (database data adj base) (camera vision))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/03 14:02
L52	79	"438"/\$ and strip with (die dice) with ((locat\$4 position) (database data adj base) (camera vision))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/03 14:02

L51	0	"716"/\$ and strip with (die dice) with ((locat\$4 position) (database data adj base) (camera vision))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/03 14:02
L50	0	"714"/\$ and strip with (die dice) with ((locat\$4 position) (database data adj base) (camera vision))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/03 14:02
L49	3	"702"/\$ and strip with (die dice) with ((locat\$4 position) (database data adj base) (camera vision))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/03 14:02
L45	5	strip with (die dice) same ((locat\$4 position) and (database data adj base) and (camera vision))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/03 14:01
L44	9	strip with (die dice) same ((locat\$4 position) and (database data adj base))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/03 13:52
L43	20	strip same (die dice) same ((locat\$4 position) and (database data adj base))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/03 13:39
L42	5	strip with (die dice) with ((locat\$4 position) and (database data adj base))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/03 13:37
L41	4	(camera vision) and strip with (die dice) with ((locat\$4 position) and (database data adj base))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/03 13:36
L40	3	"438"/\$ and (camera vision) and strip with (die dice) with ((locat\$4 position) and (database data adj base))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/03 13:35
L39	2	"257"/\$ and (camera vision) and strip with (die dice) with ((locat\$4 position) and (database data adj base))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/03 13:34

L38	0	"235"/\$ and (camera vision) and strip with (die dice) with ((locat\$4 position) and (database data adj base))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/03 13:34
L37	3	"156"/\$ and (camera vision) and strip with (die dice) with ((locat\$4 position) and (database data adj base))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/03 13:34
L36	0	"716"/\$ and (camera vision) and strip with (die dice) with ((locat\$4 position) and (database data adj base))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/03 13:34
L35	0	"702"/\$ and (camera vision) and strip with (die dice) with ((locat\$4 position) and (database data adj base))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/03 13:34
L34	1	"700"/\$ and (camera vision) and strip with (die dice) with ((locat\$4 position) and (database data adj base))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/03 13:34
L33	0	"714"/\$ and (camera vision) and strip with (die dice) with ((locat\$4 position) and (database data adj base))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/03 13:34
L28	2	"714"/\$ and (camera vision) and (strip die dice) with ((locat\$4 position) and (database data adj base))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/03 13:33
L32	5	"235"/\$ and (camera vision) and (strip die dice) with ((locat\$4 position) and (database data adj base))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/03 13:32
L31	4	"257"/\$ and (camera vision) and (strip die dice) with ((locat\$4 position) and (database data adj base))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/03 13:32
L30	6	"156"/\$ and (camera vision) and (strip die dice) with ((locat\$4 position) and (database data adj base))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/03 13:32

L29	3	"716"/\$ and (camera vision) and (strip die dice) with ((locat\$4 position) and (database data adj base))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/03 13:32
L27	5	"702"/\$ and (camera vision) and (strip die dice) with ((locat\$4 position) and (database data adj base))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/03 13:31
L26	4	"700"/\$ and (camera vision) and (strip die dice) with ((locat\$4 position) and (database data adj base))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/03 13:31
L25	16	"438"/\$ and (camera vision) and (strip die dice) with ((locat\$4 position) and (database data adj base))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/03 13:31
L24	3	"438"/\$ and (camera vision) and wafer same strip same (die dice) and (strip die dice) with ((locat\$4 position) and (database data adj base))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/03 13:31
L23	2	"257"/\$ and (camera vision) and wafer same strip same (die dice) and (strip die dice) with ((locat\$4 position) and (database data adj base))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/03 13:31
L21	3	"156"/\$ and (camera vision) and wafer same strip same (die dice) and (strip die dice) with ((locat\$4 position) and (database data adj base))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/03 13:31
L22	0	"235"/\$ and (camera vision) and wafer same strip same (die dice) and (strip die dice) with ((locat\$4 position) and (database data adj base))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/03 13:30
L20	0	"716"/\$ and (camera vision) and wafer same strip same (die dice) and (strip die dice) with ((locat\$4 position) and (database data adj base))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/03 13:30
L19	0	"714"/\$ and (camera vision) and wafer same strip same (die dice) and (strip die dice) with ((locat\$4 position) and (database data adj base))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/03 13:30

L18	0	"702"/\$ and (camera vision) and wafer same strip same (die dice) and (strip die dice) with ((locat\$4 position) and (database data adj base))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/03 13:30
L17	1	"700"/\$ and (camera vision) and wafer same strip same (die dice) and (strip die dice) with ((locat\$4 position) and (database data adj base))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/03 13:29
L16	19	(camera vision) and wafer same strip same (die dice) and (strip die dice) with ((locat\$4 position) and (database data adj base))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/03 13:28
L15	15	(camera vision) and wafer same strip same (die dice) and (strip die dice) with ((locat\$4 position) and (database data adj base)) and (@ad<"20010227" @rlad<"20010227")	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/03 13:28
L14	4	wafer with strip with (die dice) and (strip die dice) with ((locat\$4 position) and (database data adj base))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/03 13:17
L13	0	wafer with strip with (die dice) and (strip die dice) with ((locat\$4 position) and (database data adj base)) and (@ad<"20010227" @rlad<"20010227")	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/03 13:17
L11	0	(camera vision) and wafer with strip with (die dice) and (strip die dice) with ((locat\$4 position) and (database data adj base)) and (@ad<"20010227" @rlad<"20010227")	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/03 13:17
L12	4	(camera vision) and wafer with strip with (die dice) and (strip die dice) with ((locat\$4 position) and (database data adj base))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/03 13:16
L10	51	(camera vision) and wafer with (strip die dice) and (strip die dice) with ((locat\$4 position) and (database data adj base)) and (@ad<"20010227" @rlad<"20010227")	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/03 13:15

L9	53	(camera vision) and wafer same (strip die dice) and (strip die dice) with ((locat\$4 position) and (database data adj base)) and (@ad<"20010227" @rlad<"20010227")	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/03 13:13
L8	138	wafer same (strip die dice) and (strip die dice) with ((locat\$4 position) and (database data adj base)) and (@ad<"20010227" @rlad<"20010227")	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/03 13:12
L7	17	wafer same strip same (die dice) and (strip die dice) with ((locat\$4 position) and (database data adj base)) and (@ad<"20010227" @rlad<"20010227")	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/03 13:03
L6	21	wafer same strip same (die dice) and (strip die dice) with ((locat\$4 position) and (database data adj base))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/03 12:50
L5	34	wafer same strip same (die dice) and (wafer strip die dice) with ((locat\$4 position) and (database data adj base))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/03 12:43
L4	56	wafer same strip same die and (locat\$4 position) and (database data adj base)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/03 12:23
L3	605	wafer and strip and die and (locat\$4 position) and (database data adj base)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/03 12:21

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6049624 65  
6226394 65  
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6400840 65  
6730532 65  
6730545 65  
6901984 65  
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5549716 54  
5726920 54  
6100590 54  
5220724 54  
5486722 54  
5866948 54  
5981971 54  
6031292 54  
6034423 54  
6117709 54  
6194739 54  
6230569 54  
4897133 54  
4994736 54  
5296738 54  
5301143 54  
5371943 54  
5420460 54  
5423119 54  
5429992 54  
5458158 54  
5521430 54  
5610437 54  
5623123 54  
5625631 54  
5633528 54  
5675127 54  
5763057 54  
5764577 54  
5824964 54  
5838023 54  
5886362 54  
5915231 54  
5933713 54  
5956838 54  
5960260 54  
6008061 54  
6014018 54  
6031281 54  
6031724 54  
6031784 54  
6052287 54

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Titles of Most Frequently Occurring Classifications of Patents Returned  
From A Search of 10086051 on November 03, 2005

- 6 257/676 (1 OR, 5 XR)  
 Class 257 : ACTIVE SOLID-STATE DEVICES  
 257/666 LEAD FRAME  
 257/676 .With structure for mounting semiconductor chip  
           to lead frame (e.g., configuration of die bonding flag,  
           absence of a die bonding flag, recess for LED)
  
- 6 257/E23.179 (0 OR, 6 XR)  
 Class 257 : ACTIVE SOLID-STATE DEVICES  
 257/E23.176 ...For flat cards, e.g., credit cards (EPO)  
 257/E23.179 .Marks applied to semiconductor devices or  
           parts, e.g., registration marks, test patterns, alignment  
           structures, wafer maps (EPO)
  
- 5 29/827 (2 OR, 3 XR)  
 Class 029 : METAL WORKING  
 29/592 METHOD OF MECHANICAL MANUFACTURE  
 29/592.1 .Electrical device making  
 29/825 ..Conductor or circuit manufacturing  
 29/827 ...Beam lead frame or beam lead device
  
- 5 257/666 (2 OR, 3 XR)  
 Class 257 : ACTIVE SOLID-STATE DEVICES  
 257/666 LEAD FRAME
  
- 5 257/778 (2 OR, 3 XR)  
 Class 257 : ACTIVE SOLID-STATE DEVICES  
 257/734 COMBINED WITH ELECTRICAL CONTACT OR LEAD  
 257/778 .Flip chip
  
- 5 257/E23.037 (0 OR, 5 XR)  
 Class 257 : ACTIVE SOLID-STATE DEVICES  
 257/E23.001 PACKAGING, INTERCONNECTS, AND MARKINGS FOR  
           SEMICONDUCTOR OR OTHER SOLID-STATE DEVICES (EPO)  
 257/E23.01 .Arrangements for conducting electric current  
           to or from solid-state body in operation, e.g., leads,  
           terminal arrangements (EPO)  
 257/E23.023 ..Consisting of soldered or bonded  
           constructions (EPO)  
 257/E23.031 ...Lead frames or other flat leads (EPO)  
 257/E23.037 ....Characterized by die pad (EPO)
  
- 4 257/48 (4 OR, 0 XR)  
 Class 257 : ACTIVE SOLID-STATE DEVICES  
 257/48 TEST OR CALIBRATION STRUCTURE
  
- 4 382/145 (4 OR, 0 XR)  
 Class 382 : IMAGE ANALYSIS  
 382/100 APPLICATIONS  
 382/141 .Manufacturing or product inspection  
 382/145 ..Inspection of semiconductor device or printed  
           circuit board
  
- 4 702/187 (0 OR, 4 XR)  
 Class 702 : DATA PROCESSING: MEASURING, CALIBRATING, OR  
           TESTING  
 702/127 MEASUREMENT SYSTEM  
 702/187 .History logging or time stamping



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- 3 257/787 (0 OR, 3 XR)  
 Class 257 : ACTIVE SOLID-STATE DEVICES  
 257/787 ENCAPSULATED
- 3 257/E23.004 (0 OR, 3 XR)  
 Class 257 : ACTIVE SOLID-STATE DEVICES  
 257/E23.001 PACKAGING, INTERCONNECTS, AND MARKINGS FOR  
                   SEMICONDUCTOR OR OTHER SOLID-STATE DEVICES (EPO)  
 257/E23.003 .Mountings, e.g., nondetachable insulating  
                   substrates (EPO)  
 257/E23.004 ..characterized by shape (EPO)
- 3 257/E23.043 (0 OR, 3 XR)  
 Class 257 : ACTIVE SOLID-STATE DEVICES  
 257/E23.001 PACKAGING, INTERCONNECTS, AND MARKINGS FOR  
                   SEMICONDUCTOR OR OTHER SOLID-STATE DEVICES (EPO)  
 257/E23.01 .Arrangements for conducting electric current  
                   to or from solid-state body in operation, e.g., leads,  
                   terminal arrangements (EPO)  
 257/E23.023 ..Consisting of soldered or bonded  
                   constructions (EPO)  
 257/E23.031 ...Lead frames or other flat leads (EPO)  
 257/E23.043 ....Geometry of lead frame (EPO)
- 3 257/E23.067 (0 OR, 3 XR)  
 Class 257 : ACTIVE SOLID-STATE DEVICES  
 257/E23.001 PACKAGING, INTERCONNECTS, AND MARKINGS FOR  
                   SEMICONDUCTOR OR OTHER SOLID-STATE DEVICES (EPO)  
 257/E23.01 .Arrangements for conducting electric current  
                   to or from solid-state body in operation, e.g., leads,  
                   terminal arrangements (EPO)  
 257/E23.023 ..Consisting of soldered or bonded  
                   constructions (EPO)  
 257/E23.06 ...Leads, i.e., metallizations or lead frames  
                   on insulating substrates, e.g., chip carriers (EPO)  
 257/E23.067 ....Via connections through substrates, e.g.,  
                   pins going through substrate, coaxial cables (EPO)
- 3 438/123 (0 OR, 3 XR)  
 Class 438 : SEMICONDUCTOR DEVICE MANUFACTURING: PROCESS  
 438/106 PACKAGING (E.G., WITH MOUNTING, ENCAPSULATING,  
                   ETC.) OR TREATMENT OF PACKAGED SEMICONDUCTOR  
 438/121 .Metallic housing or support  
 438/123 ..Lead frame
- 3 438/14 (0 OR, 3 XR)  
 Class 438 : SEMICONDUCTOR DEVICE MANUFACTURING: PROCESS  
 438/14 WITH MEASURING OR TESTING
- 3 438/18 (1 OR, 2 XR)  
 Class 438 : SEMICONDUCTOR DEVICE MANUFACTURING: PROCESS  
 438/14 WITH MEASURING OR TESTING  
 438/17 .Electrical characteristic sensed  
 438/18 ..Utilizing integral test element
- 2 29/566.3 (1 OR, 1 XR)  
 Class 029 : METAL WORKING  
 29/33R PLURAL DIVERSE MANUFACTURING APPARATUS  
                   INCLUDING MEANS FOR METAL SHAPING OR ASSEMBLING  
 29/566 .Including composite tool

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- 29/566.1 ..Including severing means  
29/566.3 ...To trim electric component
- 2 29/740 (0 OR, 2 XR)  
Class 029 : METAL WORKING  
29/700 MEANS TO ASSEMBLE OR DISASSEMBLE  
29/729 .Means to assemble electrical device  
29/739 ..Means to fasten electrical component to  
wiring board, base, or substrate  
29/740 ...Chip component
- 2 29/840 (1 OR, 1 XR)  
Class 029 : METAL WORKING  
29/592 METHOD OF MECHANICAL MANUFACTURE  
29/592.1 .Electrical device making  
29/825 ..Conductor or circuit manufacturing  
29/829 ...On flat or curved insulated base, e.g.,  
printed circuit, etc.  
29/832 ....Assembling to base an electrical component,  
e.g., capacitor, etc.  
29/840 .....By metal fusion
- 2 29/841 (1 OR, 1 XR)  
Class 029 : METAL WORKING  
29/592 METHOD OF MECHANICAL MANUFACTURE  
29/592.1 .Electrical device making  
29/825 ..Conductor or circuit manufacturing  
29/829 ...On flat or curved insulated base, e.g.,  
printed circuit, etc.  
29/832 ....Assembling to base an electrical component,  
e.g., capacitor, etc.  
29/841 .....With encapsulating, e.g., potting, etc.
- 2 156/64 (1 OR, 1 XR)  
Class 156 : ADHESIVE BONDING AND MISCELLANEOUS CHEMICAL  
MANUFACTURE  
156/1 METHODS  
156/60 .Surface bonding and/or assembly therefor  
156/64 ..With measuring, testing, or inspecting
- 2 174/52.2 (1 OR, 1 XR)  
Class 174 : ELECTRICITY: CONDUCTORS AND INSULATORS  
174/50 BOXES AND HOUSINGS  
174/52.1 .With electric device or mounting means  
therefor  
174/52.2 ..Potted or encapsulated
- 2 257/673 (0 OR, 2 XR)  
Class 257 : ACTIVE SOLID-STATE DEVICES  
257/666 LEAD FRAME  
257/673 .With bumps on ends of lead fingers to connect  
to semiconductor
- 2 257/737 (0 OR, 2 XR)  
Class 257 : ACTIVE SOLID-STATE DEVICES  
257/734 COMBINED WITH ELECTRICAL CONTACT OR LEAD  
257/737 .Bump leads
- 2 257/758 (1 OR, 1 XR)  
Class 257 : ACTIVE SOLID-STATE DEVICES  
257/734 COMBINED WITH ELECTRICAL CONTACT OR LEAD  
257/741 .Of specified material other than unalloyed  
aluminum

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257/750 ...Layered  
 257/758 ...Multiple metal levels on semiconductor,  
 separated by insulating layer (e.g., multiple level  
 metallization for integrated circuit)

2 257/E21.505 (0 OR, 2 XR)

Class 257 : ACTIVE SOLID-STATE DEVICES

257/E21.001 PROCESSES OR APPARATUS ADAPTED FOR MANUFACTURE  
 OR TREATMENT OF SEMICONDUCTOR OR SOLID-STATE DEVICES

OR OF

PARTS THEREOF (EPO)

257/E21.002 .Manufacture or treatment of semiconductor  
 device (EPO)

257/E21.04 ..Device having at least one potential-jump  
 barrier or surface barrier, e.g., PN junction,

depletion

layer, carrier concentration layer (EPO)

257/E21.499 ...Assembling semiconductor devices, e.g.,  
 packaging, including mounting, encapsulating, or

treatment

of packaged semiconductor (EPO)

257/E21.505 ....Insulative mounting semiconductor device on  
 support (EPO)

2 257/E21.525 (0 OR, 2 XR)

Class 257 : ACTIVE SOLID-STATE DEVICES

257/E21.515 .....Involving use of mechanical auxiliary part  
 without use of alloying or soldering process, e.g.,  
 pressure contacts (EPO)

257/E21.521 .Testing or measuring during manufacture or  
 treatment or reliability measurement, i.e., testing of  
 parts followed by no processing which modifies parts as  
 such (EPO)

257/E21.525 ..Procedures, i.e., sequence of activities  
 consisting of plurality of measurement and correction,  
 marking or sorting steps (EPO)

2 257/E23.038 (0 OR, 2 XR)

Class 257 : ACTIVE SOLID-STATE DEVICES

257/E23.001 PACKAGING, INTERCONNECTS, AND MARKINGS FOR  
 SEMICONDUCTOR OR OTHER SOLID-STATE DEVICES (EPO)

257/E23.01 .Arrangements for conducting electric current  
 to or from solid-state body in operation, e.g.,

leads,

terminal arrangements (EPO)

257/E23.023 ..Consisting of soldered or bonded  
 constructions (EPO)

257/E23.031 ...Lead frames or other flat leads (EPO)

257/E23.037 ....Characterized by die pad (EPO)

257/E23.038 .....Insulative substrate being used as die  
 pad, e.g., ceramic, plastic (EPO)

2 257/E23.046 (0 OR, 2 XR)

Class 257 : ACTIVE SOLID-STATE DEVICES

257/E23.001 PACKAGING, INTERCONNECTS, AND MARKINGS FOR  
 SEMICONDUCTOR OR OTHER SOLID-STATE DEVICES (EPO)

257/E23.01 .Arrangements for conducting electric current  
 to or from solid-state body in operation, e.g.,

leads,

terminal arrangements (EPO)

257/E23.023 ..Consisting of soldered or bonded  
 constructions (EPO)

257/E23.031 ...Lead frames or other flat leads (EPO)

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- 257/E23.043 ....Geometry of lead frame (EPO)
- 257/E23.046 .....Cross-section geometry (EPO)
- 2 257/E23.068 (0 OR, 2 XR)
  - Class 257 : ACTIVE SOLID-STATE DEVICES
  - 257/E23.001 PACKAGING, INTERCONNECTS, AND MARKINGS FOR SEMICONDUCTOR OR OTHER SOLID-STATE DEVICES (EPO)
  - 257/E23.01 .Arrangements for conducting electric current to or from solid-state body in operation, e.g., leads, terminal arrangements (EPO)
  - 257/E23.023 ..Consisting of soldered or bonded constructions (EPO)
  - 257/E23.06 ...Leads, i.e., metallizations or lead frames on insulating substrates, e.g., chip carriers (EPO)
  - 257/E23.068 ....Additional leads joined to metallizations on insulating substrate, e.g., pins, bumps, wires, flat leads (EPO)
- 2 257/E23.125 (0 OR, 2 XR)
  - Class 257 : ACTIVE SOLID-STATE DEVICES
  - 257/E23.113 ....Ceramic materials or glass (EPO)
  - 257/E23.116 .Encapsulations, e.g., encapsulating layers, coatings, e.g., for protection (EPO)
  - 257/E23.123 ..Characterized by arrangement or shape (EPO)
  - 257/E23.124 ...Device being completely enclosed (EPO)
  - 257/E23.125 ....Substrate forming part of encapsulation (EPO)
- 2 324/73.1 (0 OR, 2 XR)
  - Class 324 : ELECTRICITY: MEASURING AND TESTING
  - 324/73.1 PLURAL, AUTOMATICALLY SEQUENTIAL TESTS
- 2 324/765 (1 OR, 1 XR)
  - Class 324 : ELECTRICITY: MEASURING AND TESTING
  - 324/500 FAULT DETECTING IN ELECTRIC CIRCUITS AND OF ELECTRIC COMPONENTS
  - 324/537 .Of individual circuit component or element
  - 324/765 ..Test of semiconductor device
- 2 361/764 (0 OR, 2 XR)
  - Class 361 : ELECTRICITY: ELECTRICAL SYSTEMS AND DEVICES
  - 361/600 HOUSING OR MOUNTING ASSEMBLIES WITH DIVERSE ELECTRICAL COMPONENTS
  - 361/679 .For electronic systems and devices
  - 361/748 ..Printed circuit board
  - 361/760 ...Connection of components to board
  - 361/761 ....Component within printed circuit board
  - 361/764 .....Integrated circuit
- 2 438/106 (0 OR, 2 XR)
  - Class 438 : SEMICONDUCTOR DEVICE MANUFACTURING: PROCESS
  - 438/106 PACKAGING (E.G., WITH MOUNTING, ENCAPSULATING, ETC.) OR TREATMENT OF PACKAGED SEMICONDUCTOR
- 2 438/613 (0 OR, 2 XR)
  - Class 438 : SEMICONDUCTOR DEVICE MANUFACTURING: PROCESS
  - 438/584 COATING WITH ELECTRICALLY OR THERMALLY CONDUCTIVE MATERIAL
  - 438/597 .To form ohmic contact to semiconductive

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material

438/612 ..Forming solder contact or bonding pad  
438/613 ...Bump electrode

2 438/622 (0 OR, 2 XR)

Class 438 : SEMICONDUCTOR DEVICE MANUFACTURING: PROCESS

438/584 COATING WITH ELECTRICALLY OR THERMALLY  
CONDUCTIVE MATERIAL

438/597 .To form ohmic contact to semiconductive  
material

438/618 ..Contacting multiple semiconductive regions  
(i.e., interconnects)

438/622 ...Multiple metal levels, separated by  
insulating layer (i.e., multiple level metallization)

2 700/121 (1 OR, 1 XR)

Class 700 : DATA PROCESSING: GENERIC CONTROL SYSTEMS OR  
SPECIFIC APPLICATIONS

700/90 SPECIFIC APPLICATION, APPARATUS OR PROCESS

700/95 .Product assembly or manufacturing

700/117 ..Particular manufactured product or operation

700/121 ...Integrated circuit production or  
semiconductor fabrication